



Electronic Filing System (EFS) Data

Electronic Patent Application Submission

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Application ID: 10669820
Title of Invention: REINFORCED DIE PAD SUPPORT
STRUCTURE
First Named Inventor: Chung Tzu
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Attorney Docket Number: AMKOR090A



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Electronic Version v1.1
Stylesheet Version v1.1.0

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| Title of Invention | REINFORCED DIE PAD SUPPORT STRUCTURE | |
| Application Number: | 10/669820  | |
| Date: | 2003-09-24 | |
| First Named Applicant: | Chung Hsing Tzu | |
| Confirmation Number: | 5197 | |
| Attorney Docket Number: | AMKOR090A | |
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| Submitted by: | Elec. Sign. | Sign. Capacity |
| Mark B. Garred Registered Number: 34,823 | /mbg/ | Attorney |
| Documents being submitted us-ids | Files ids6-usidst.xml us-ids.dtd us-ids.xsl | |
| Comments | | |



ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18

Stylesheet Version v18.0

| Title of Invention | REINFORCED DIE PAD SUPPORT STRUCTURE | | | | |
|---|--|------------|------------|-----------------|----------|
| Application Number: | 10/669820  | | | | |
| Confirmation Number: | 5197 | | | | |
| First Named Applicant: | Chung Tzu | | | | |
| Attorney Docket Number: | AMKOR090A | | | | |
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Signature

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| Examiner Name | Date |
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